

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/16069	
1.3 Title of PCN	Amkor ATP (Philippines) LQFP 14x14 package Copper Palladium bonding wire introduction on STM32G47x and STM32G48x listed products.	
1.4 Product Category	STM32G471x, STM32G473x, STM32G474x, STM32G483x and STM32G484x.	
1.5 Issue date	2026-06-30	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Marie TOURNUT
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	Direct Material: Bond Wire - Metallurgy (metallic composition/ raw material)	Amkor ATP (Philippines)

4. Description of change

	Old	New
4.1 Description	Current Wire bonding material: - ASE KaoHsiung (Taiwan) gold wire - Amkor ATP (Philippines) gold wire	Current Wire bonding material: - ASE KaoHsiung (Taiwan) gold wire - Amkor ATP (Philippines) gold wire New Wire bonding material : - Amkor ATP (Philippines) copper palladium wire
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no impact on form, Fit, Function	

5. Reason / motivation for change

5.1 Motivation	To improve service
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Traceability ensured by ST Internal tools
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7. Timing / schedule

7.1 Date of qualification results	2026-06-26
7.2 Intended start of delivery	2026-09-28
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	16069 MDRF-GPM-RER2312 V4.0 PCN14039_16069_ATP LQFP14 LQFP20 - CuPd RER.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2026-06-30

9. Attachments (additional documentations)		
16069 Public product.pdf 16069 MDRF-GPM-RER2312 V4.0 PCN14039_16069_ ATP LQFP14 LQFP20 - CuPd RER.pdf 16069 _Additional information.pdf		
10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32G474QET6	
	STM32G483QET6	

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